

Vishay Siliconix

# Automotive P-Channel 40 V (D-S) 175 °C MOSFET

#### COT 00 (TO 000)



Marking Code: 9UYXX

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-40				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.094				
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -4.5 V	0.188				
I <sub>D</sub> (A)	-4.1				
Configuration	Single				

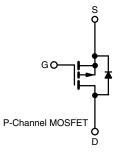
#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rg and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



ORDERING INFORMATION	
Package	SOT-23
Lead (Pb)-free and halogen-free	SQ2389CES (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

ABSOLUTE MAXIMUM RATING	<b>S</b> ( $T_C = 25  ^{\circ}C$ , unles	s otherwise noted	(k	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	-40	V
Gate-source voltage		V <sub>GS</sub>	± 20	V
Continuous drain current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	-4.1	
	T <sub>C</sub> = 125 °C		-2.4	
Continuous source current (diode conduction)		I <sub>S</sub>	-3.6	Α
Pulsed drain current <sup>a</sup>		I <sub>DM</sub>	-16	
Single pulse avalanche current		I <sub>AS</sub>	-12	
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ
Maximum power dissipation	T <sub>C</sub> = 25 °C	D	3	W
	T <sub>C</sub> = 125 °C	$P_{D}$	1	VV
Operating junction and storage temperature	range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-ambient	PCB mount b	$R_{thJA}$	166	°C/W		
Junction-to-foot (drain)		R <sub>thJF</sub>	50	C/VV		

#### Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %
- b. When mounted on 1" square PCB (FR4 material)



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							L
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-40	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1.5	-2.0	-2.5	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V	-	-	-1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V, T <sub>J</sub> = 125 °C	-	_	-50	μA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V, T <sub>J</sub> = 175 °C	-	-	-150	·
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	V <sub>DS</sub> ≤ -5 V	-10	-	-	Α
	5(0.1)	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A	-	0.084	0.094	Ω
		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A, T <sub>J</sub> = 125 °C	-	-	0.144	
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A, T <sub>J</sub> = 175 °C	-	-	0.169	
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -3 A	-	0.140	0.188	
Forward transconductance b	9 <sub>fs</sub>		= -10 V, I <sub>D</sub> = -3 A	-	5	-	S
Dynamic b							
Input capacitance	C <sub>iss</sub>			-	414	455	
Output capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -20 V, f = 1 MHz	-	80	100	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	42	54	
Total gate charge <sup>c</sup>	Qg			-	8.2	12	
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$V_{DS} = -20 \text{ V}, I_{D} = -3 \text{ A}$	-	1.1	-	nC
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>			-	3.0	-	
Gate resistance	$R_g$	f = 1 MHz		3.1	4.1	7	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	7	10	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = -20 V, $R_L$ = 6.7 $\Omega$ $I_D$ $\cong$ -3 A, $V_{GEN}$ = -10 V, $R_g$ = 1 $\Omega$		-	12	16	ns
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			_	16	20	
Fall time <sup>c</sup>	t <sub>f</sub>			-	4	8	
Source-Drain Diode Ratings and Characteristics b							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	-10	Α
Forward voltage	$V_{SD}$	I <sub>F</sub> = -1.5 A, V <sub>GS</sub> = 0 V		-	-0.8	-1.2	V
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -2 A, di/dt = 100 A/μs		_	17	34	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	14	28	nC
Reverse recovery fall time	ta			-	14	-	ns
Reverse recovery rise time	t <sub>b</sub>				3	-	
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>			-	-1.99	-	Α

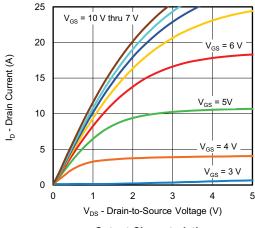
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

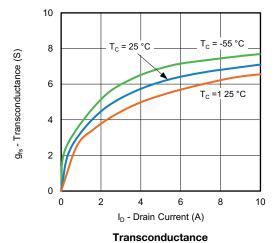
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

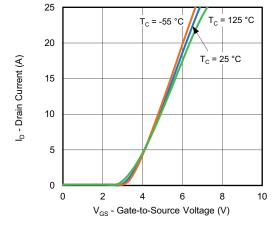


## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



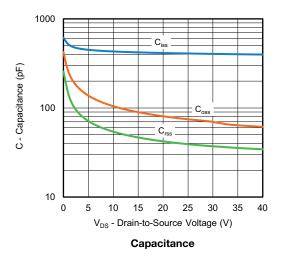
#### **Output Characteristics**

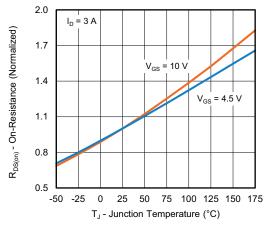




**Transfer Characteristics** 

**On-Resistance vs. Drain Current** 

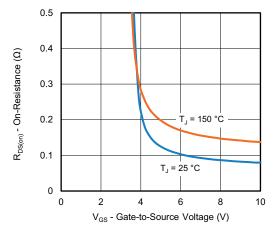




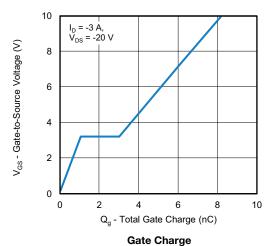
**On-Resistance vs. Junction Temperature** 

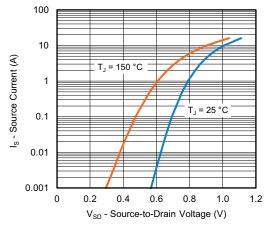


## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

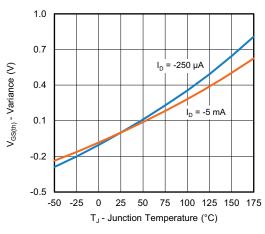


On-Resistance vs. Gate-Source Voltage

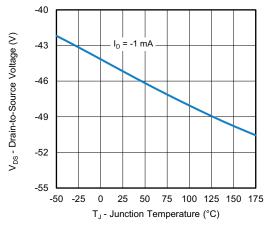




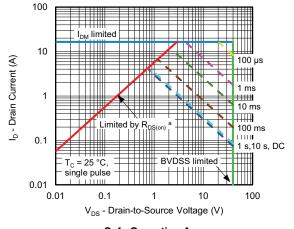
Source-Drain Diode Forward Voltage



**Threshold Voltage** 



**Drain Source Breakdown vs. Junction Temperature** 

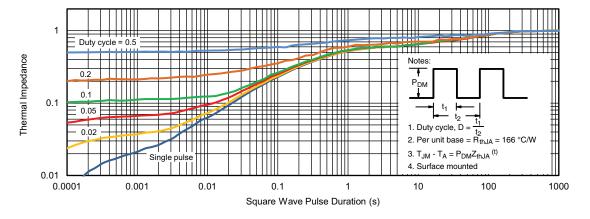


Safe Operating Area

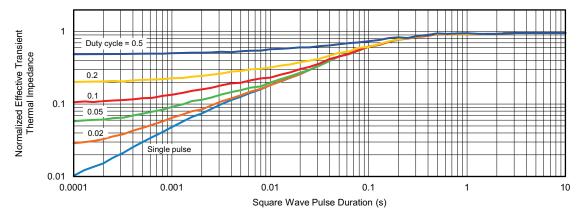
a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



### Normalized Thermal Transient Impedance, Junction-to-Foot

#### **Notes**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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## SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

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### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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